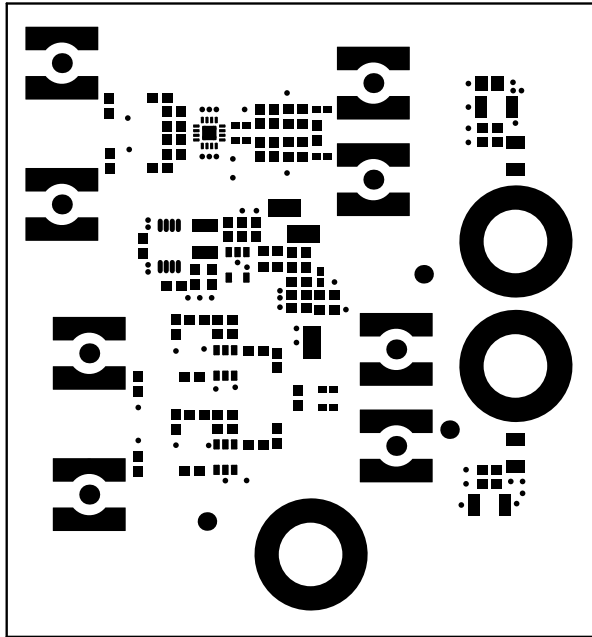
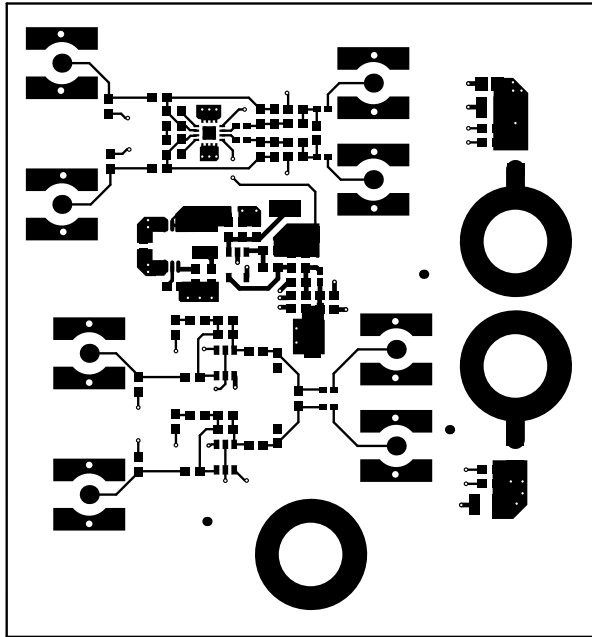


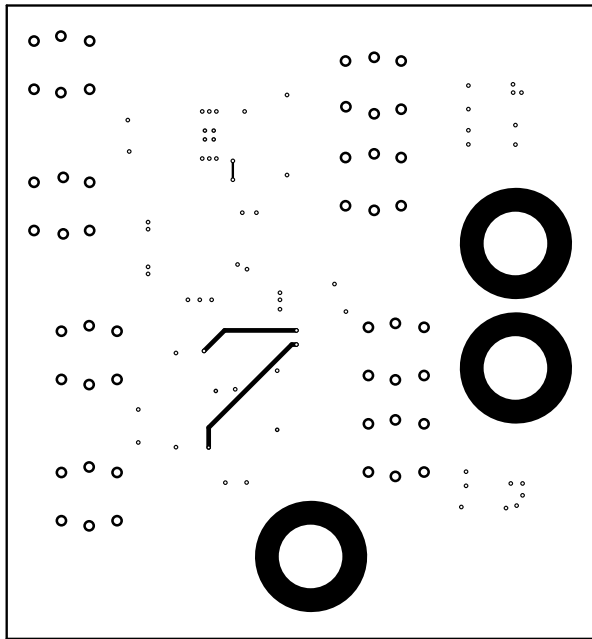
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01053		
PLOT NAME = Top Overlay	GENERATED : 3/30/2017 5:01:44 PM	TEXAS INSTRUMENTS	



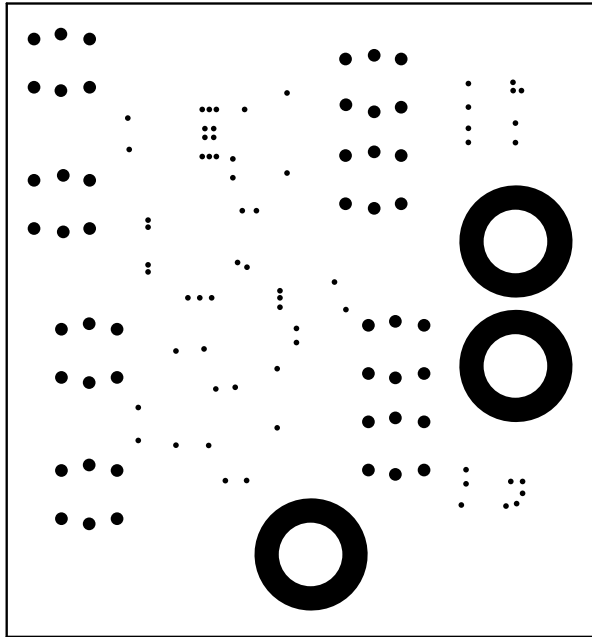
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01053		
PLOT NAME = Top Solder Mask	GENERATED : 3/30/2017 5:01:45 PM	TEXAS INSTRUMENTS	



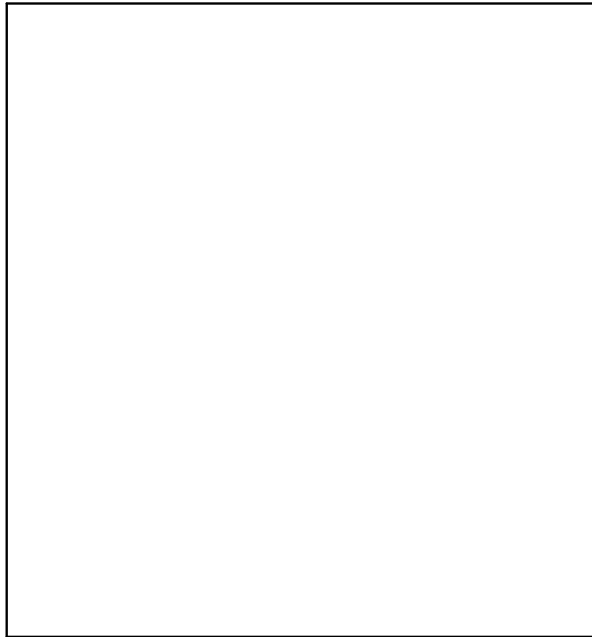
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01053		
PLOT NAME = Top Layer	GENERATED : 3/30/2017 5:01:46 PM	TEXAS INSTRUMENTS	



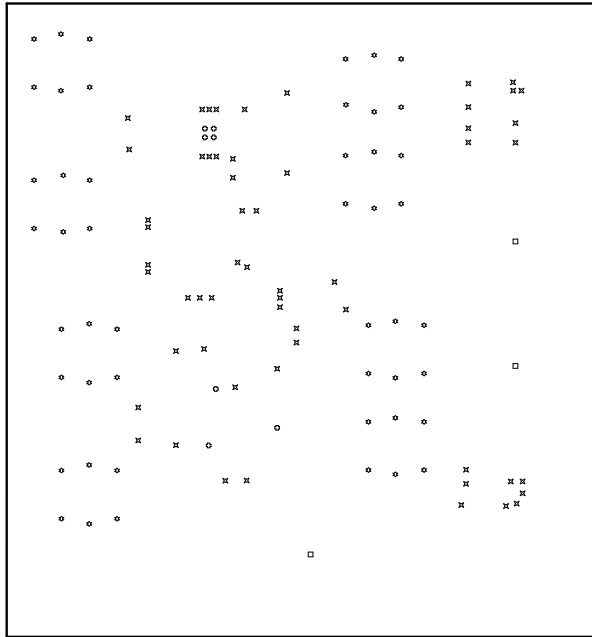
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01053		
PLOT NAME = Bottom Layer	GENERATED : 3/30/2017 5:01:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01053		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/30/2017 5:01:48 PM	TEXAS INSTRUMENTS	

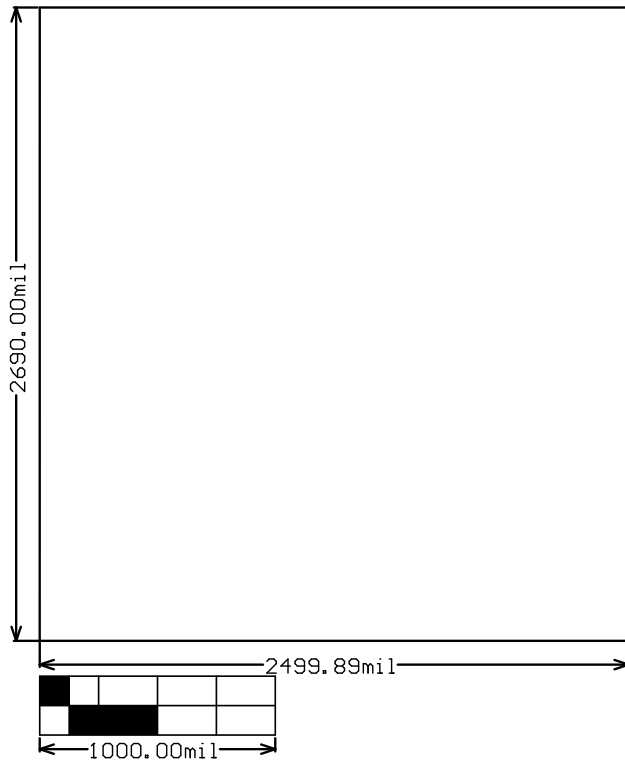


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01053		
PLOT NAME = Bottom Overlay	GENERATED : 3/30/2017 5:01:49 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	7	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	57	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	48	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
□	3	270.00mil (6.858mm)	PTH	Round	Top Layer - Bottom Layer	
	115 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01053		
PLOT NAME = Drill Drawing	GENERATED : 3/30/2017 5:01:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01053		
PLOT NAME = Board Dimensions	GENERATED : 3/30/2017 5:01:51 PM	TEXAS INSTRUMENTS	



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